

AMENDMENTS TO THE CLAIMS

Claim 1. (canceled)

2. (previously presented) The imaging device of claim 7, wherein said photosensitive elements are arranged in a two-dimensional array.

3. (previously presented) The imaging device of claim 7, wherein said transparent material includes injection molded epoxy resin.

4. (previously presented) The imaging device of claim 7, further comprising leads connected to said semiconductor imaging chip, said leads being partially encapsulated in said transparent material.

Claims 5-6. (canceled)

7. (currently amended) An imaging device, comprising:

a frame having a support structure;

a semiconductor imaging chip supported by said support structure, said semiconductor imaging chip having an array of photosensitive elements configured to receive an image and generate a plurality of corresponding image signals;

a package encapsulating said frame, support structure, and semiconductor imaging chip in a transparent material, said transparent material covering said chip, said photosensitive elements receiving said image through said transparent material; ~~and an optical light transmitting device wherein at least a portion of said transparent~~ material supported in line with an image being received by said photosensitive elements of said semiconductor imaging chip is tinted to provide colored light filtering.

8. (currently amended) The imaging device of claim 7, further comprising an optical light transmitting device, wherein said optical light transmitting device is formed of said transparent material.

9. (currently amended) The imaging device of claim [[7]] 8 wherein said optical light transmitting device is a ~~color filter~~ lens, said ~~filter~~ lens being formed by ~~color tinting~~ of said transparent material.

10. (previously presented) The imaging device of claim 7, further comprising a color filter array molded into and encased by said transparent material.

11. (currently amended) An imaging system, comprising:

a transmitting system for transmitting an image including an image source, said ~~image source~~ transmitting system being arranged to transmit the entire image simultaneously onto each of a plurality of imaging devices;

wherein each of said plurality of imaging devices includes a semiconductor device including an array of photosensitive elements, each semiconductor device being mounted on a respective frame, each of said frames having a support structure, each of said semiconductor devices receiving said image and generating corresponding signals; and

wherein each said frame, support structure, and respective semiconductor device is encapsulated in a respective package for protecting and supporting each said semiconductor device, each of said packages being formed of transparent material, said transparent material including injection molded resin for transmitting the image from said image source onto said semiconductor devices.

12. (original) The system of claim 11, wherein said image source includes a lens.

13. (previously presented) The system of claim 11 wherein said semiconductor imaging devices include complementary color filters.

14. (previously presented) The system of claim 13, wherein said complementary color filters are molded into said packages.

15. (previously presented) The system of claim 13, wherein said packages include red, green and blue filters.

16. (previously presented) The system of claim 13, wherein said packages include cyan, magenta and yellow filters.

Claims 17-27. (canceled)

28. (currently amended) An imaging device, comprising:

a housing having a cavity defined by side walls and a bottom surface;

a semiconductor imaging chip located within said cavity of said housing, said semiconductor imaging chip including an array of photosensitive elements configured to receive an image and generate corresponding signals, said photosensitive elements being covered by a transparent cover;

said semiconductor imaging chip being encapsulated in a transparent material, wherein said transparent material is disposed within said cavity and is contained by ~~has an uppermost surface substantially planar to an uppermost surface of~~ said side walls of said housing; and

an optical light transmitting device supported in line with an image being received by said photosensitive elements.

29. (previously presented) The device of claim 28, wherein said transparent cover includes a color filter.

Claim 30. (canceled)

31. (previously presented) The imaging device of claim 28, wherein said housing is formed of molded plastic.

32. (previously presented) The imaging device of claim 7, wherein said optical light transmitting device is a lens, said lens being formed of said transparent material.

33. (previously presented) The imaging device of claim 28, wherein said housing is formed of a ceramic material.

34. (previously presented) The imaging device of claim 7, wherein said optical light transmitting device is a color filter, said color filter being supported separate from said package of said transparent material.

35. (new) The imaging device of claim 28, wherein said transparent material has an uppermost surface substantially planar to an uppermost surface of said sidewalls of said housing.